

IN THE SPECIFICATION

A. Please delete paragraph [0048] in its entirety.

B. Please amend the following paragraphs as indicated:

[0049] Figures ~~[[14A-B]]~~ 13-14 are top and sectional views of another embodiment of a conductive article;

[0204] Figures ~~[[14A-B]]~~ 13-14 are top and sectional views of another embodiment of a conductive article 1400. The conductive article 1400 includes abrasive features extending from a polishing surface 1402 of a conductive portion 1404 of the conductive article 1400. The abrasive features may be abrasive particles as described with reference to Figure 3 above, or may be discrete abrasive elements 1406 as shown in Figures ~~[[14A-B]]~~ 13-14.

[0205] In one embodiment, the abrasive elements 1406 are bars received in respective slots 1408 formed in the polishing surface 1402 of the conductive article 1400. The abrasive elements 1406 generally extend from the polishing surface 1402 and are configured to remove the passivation layer of the metal surface of the substrate being polished, thereby exposing the underlying metal to the electrolyte and electrochemical activity, thereby enhancing the rate of polishing during processing. The abrasive elements 1406 may be formed from ceramic, inorganic, organic, or polymer material strong enough to break the passivation layer formed at the metal surface. An example is a bar or strip made from conventional polishing pad such as polyurethane pad disposed in the conductive article 1400. In the embodiment depicted in Figures ~~[[14A-B]]~~ 13-14, the abrasive elements 1406 may have hardness of at least about 30 Shore D, or hard enough to abrade the passivation layer of the material being polished. In one embodiment, the abrasive elements 1406 are harder than copper. Polymer particles may be

solid or spongy to tailor the wear rate of the abrasive elements 1406 relative to the surrounding conductive portion 1404.